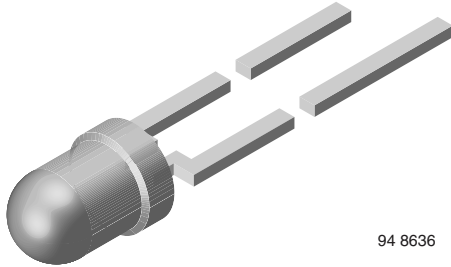




High Power Infrared Emitting Diode, 940 nm, GaAlAs, MQW



FEATURES

- Package type: leaded
- Package form: T-1
- Dimensions (in mm): $\varnothing 3$
- Peak wavelength: $\lambda_p = 940$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 25^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Good spectral matching with Si photodetectors
- Package matches with detector TEFT4300
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



DESCRIPTION

TSAL4400 is an infrared, 940 nm emitting diode in GaAlAs, MQW technology with high radiant power molded in a blue-gray plastic package.

APPLICATIONS

- Infrared remote control units
- Free air transmission systems
- Infrared source for optical counters and card readers

| PRODUCT SUMMARY | | | | |
|-----------------|---------------|--------------|------------------|------------|
| COMPONENT | I_e (mW/sr) | ϕ (deg) | λ_p (nm) | t_r (ns) |
| TSAL4400 | 36 | ± 25 | 940 | 15 |

Note

- Test conditions see table "Basic Characteristics"

| ORDERING INFORMATION | | | |
|----------------------|-----------|------------------------------|--------------|
| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
| TSAL4400 | Bulk | MOQ: 5000 pcs, 5000 pcs/bulk | T-1 |
| TSAL4400-RSZ | Ammopack | MOQ: 8000 pcs, 2000 pcs/box | T-1 |

Note

- MOQ: minimum order quantity

| ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified) | | | | |
|---|--|------------|-------------|------------------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| Reverse voltage | | V_R | 5 | V |
| Forward current | | I_F | 100 | mA |
| Peak forward current | $t_p/T = 0.5, t_p = 100 \mu\text{s}$ | I_{FM} | 200 | mA |
| Surge forward current | $t_p = 100 \mu\text{s}$ | I_{FSM} | 1.5 | A |
| Power dissipation | | P_V | 160 | mW |
| Junction temperature | | T_j | 100 | $^\circ\text{C}$ |
| Operating temperature range | | T_{amb} | -40 to +85 | $^\circ\text{C}$ |
| Storage temperature range | | T_{stg} | -40 to +100 | $^\circ\text{C}$ |
| Soldering temperature | $t \leq 5$ s, 2 mm from case | T_{sd} | 260 | $^\circ\text{C}$ |
| Thermal resistance junction / ambient | J-STD-051, leads 7 mm, soldered on PCB | R_{thJA} | 300 | K/W |

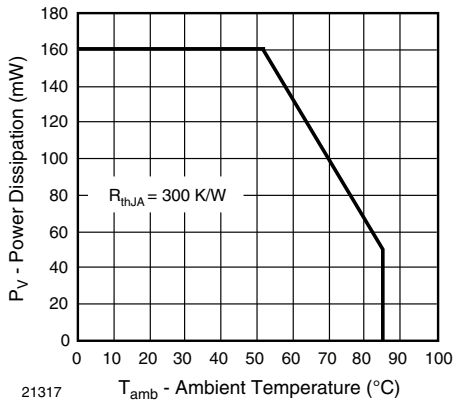


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

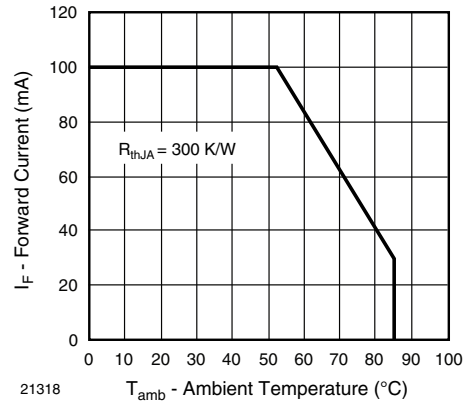


Fig. 2 - Forward Current Limit vs. Ambient Temperature

| BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | |
|--|---|------------------|------|----------|------|---------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Forward voltage | $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$ | V_F | - | 1.35 | 1.6 | V |
| | $I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$ | V_F | - | 2.6 | 3 | V |
| Temperature coefficient of V_F | $I_F = 1\text{ mA}$ | TK_{V_F} | - | -1.8 | - | mV/K |
| Reverse current | $V_R = 5\text{ V}$ | I_R | - | - | 10 | μA |
| Junction capacitance | $V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ | C_j | - | 60 | - | pF |
| Radiant intensity | $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$ | I_e | 16 | 36 | 80 | mW/sr |
| | $I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$ | I_e | 135 | 290 | - | mW/sr |
| Radiant power | $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$ | ϕ_e | - | 40 | - | mW |
| Temperature coefficient of ϕ_e | $I_F = 20\text{ mA}$ | TK_{ϕ_e} | - | -0.6 | - | %/K |
| Angle of half intensity | | φ | - | ± 25 | - | deg |
| Peak wavelength | $I_F = 100\text{ mA}$ | λ_p | - | 940 | - | nm |
| Spectral bandwidth | $I_F = 100\text{ mA}$ | $\Delta\lambda$ | - | 25 | - | nm |
| Temperature coefficient of λ_p | $I_F = 100\text{ mA}$ | TK_{λ_p} | - | 0.25 | - | nm/K |
| Rise time | $I_F = 100\text{ mA}$ | t_r | - | 15 | - | ns |
| Fall time | $I_F = 100\text{ mA}$ | t_f | - | 15 | - | ns |

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

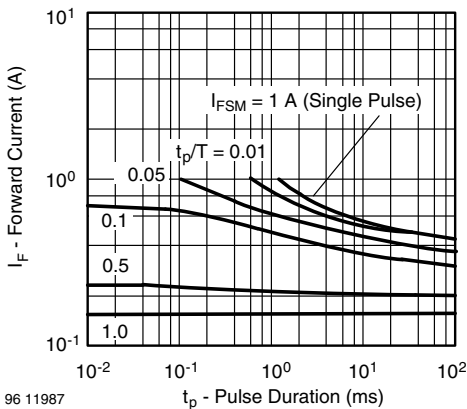


Fig. 3 - Pulse Forward Current vs. Pulse Duration

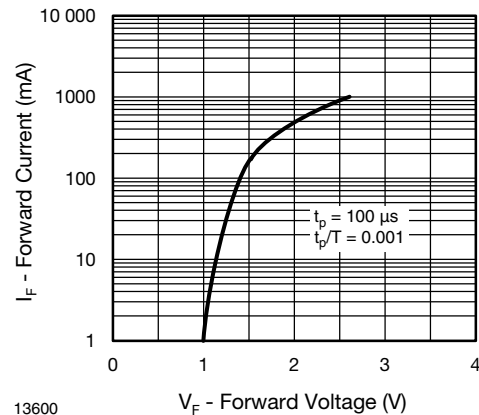


Fig. 4 - Forward Current vs. Forward Voltage

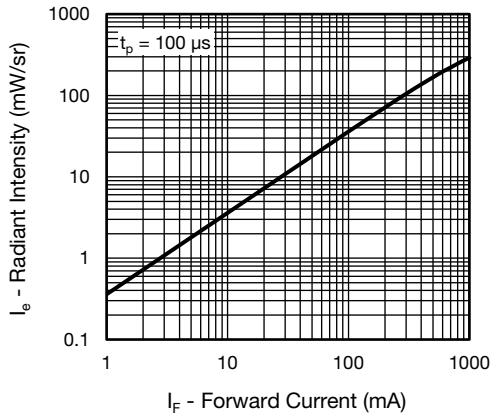


Fig. 5 - Radiant Intensity vs. Forward Current

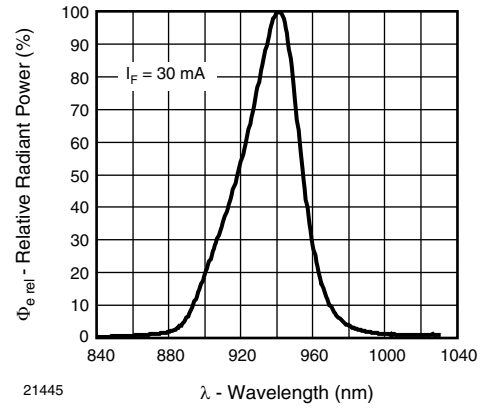


Fig. 8 - Relative Radiant Power vs. Wavelength

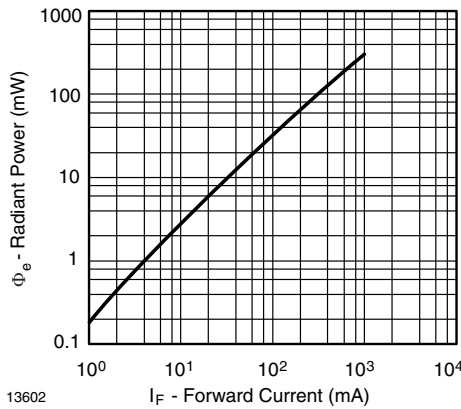


Fig. 6 - Radiant Power vs. Forward Current

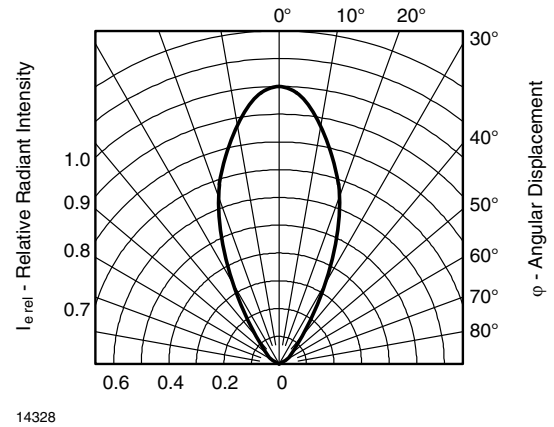


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

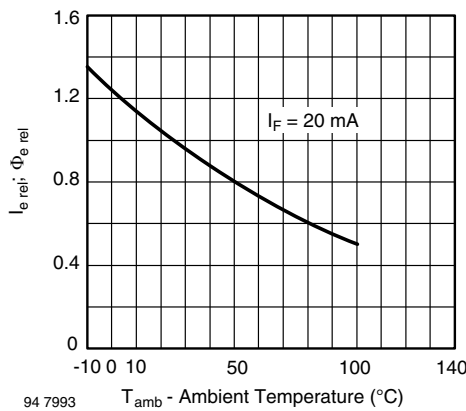
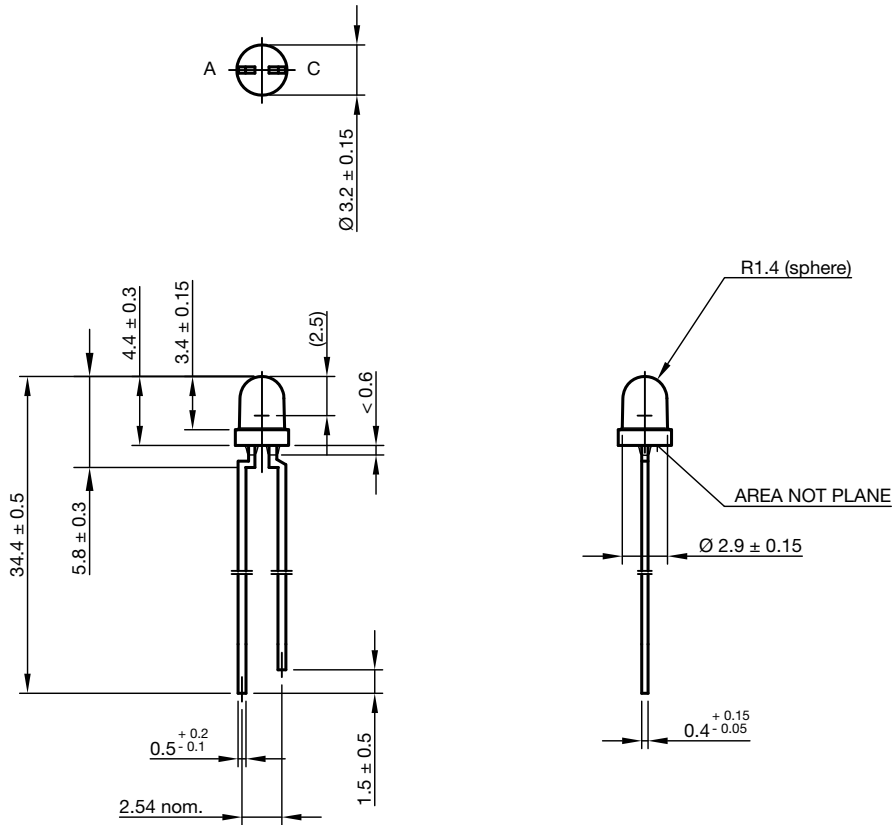


Fig. 7 - Rel. Radiant Intensity/Power vs. Ambient Temperature



PACKAGE DIMENSIONS in millimeters



technical drawings
according to DIN
specifications

Drawing-No.: 6.544-5255.01-4
Issue: 9; 28.07.14



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